ZEBAX TECHNOLOGIES

Full line of breakout adapters Mictor, Samtec, FCI, FMC Vita 57.1 Mezzanine Cards, PCIe M.2/NGFF HDMI USB Electrical test modules.

Volume 3, Issue 4

NEWS LETTER

2nd Generation of HSIC USB 2.0 SuperSpeed USB 3.0 test board (Breakout Adapter), exceptional insertion loss & introduction of uAB Plug Module

HSIC USB 2.0 SuperSpeed USB 3.0 test board (Breakout Adapter)

Zebax offers High Speed Inter-Chip , HSIC USB 2.0, SuperSpeed USB 3.0 test board tailored for debugging, development and characterization applications. ZX230 product line offers test board functionality for characterization of USB 2.0 USB 3.0, both Host and Cabling systems. "ZX230 Bundle" offers feature reach headers & stuffing option providing **best in class** module for eye diagram testing, Jitter Analysis DLL, RX Jitter, LFPS TX, LFPS RX analysis as well as USB 2.0 USB 3.0 meeting 10GHz signal bandwidth - Pre-Electrical compliance test. Power measurements can be conducted using the accessible headers.

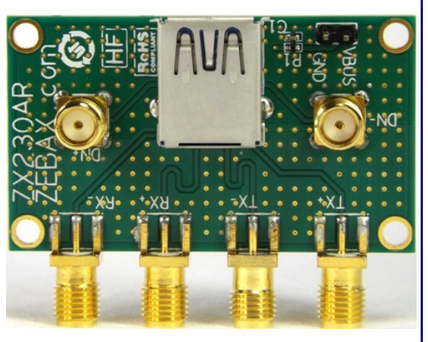
Application: Functional and interface testing of ASIC, Signal characterization, performance analysis., pre-bringup.

ZX230AP

Introducing 2nd generation of ZX230AP, best in class SuperSpeed USB 3.0 (Backward compatible with HSIC USB 2.0) test board. Using USB 3.0 **Type A Plug** connector meeting electrical compliance testing—eye diagram, jitter (random) deterministic, total jitter, SCC profiles tests, Slew Voltage levels and more). Designed In 4 layers 100 Ω differential trace impedance measuring insertion loss of 3.8dB at 5GHz bandwidth exceeding USB 3.0 test board measurement requirements.

Application: Functional and interface testing of ASIC, Signal characterization, performance analysis, pre-bringup, pre-compliance test.

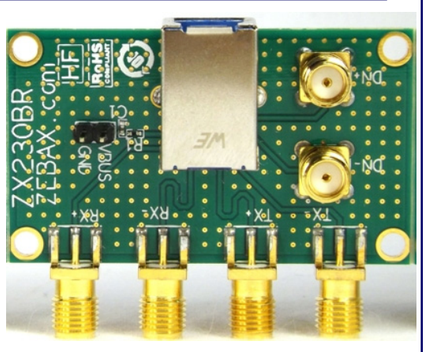
ZX230AR



2nd generation of ZX230AR, best in class SuperSpeed USB 3.0 (Backward compatible with HSIC USB 2.0) test board. Using USB 3.0 **Type A Receptacle** (Socket) connector meeting electrical compliance testing—eye diagram, jitter (random) deterministic, total jitter, SCC profiles tests, Slew Voltage levels and more). Designed In 4 layers 100 Ω differential trace impedance measuring insertion loss of 3.8dB at 5GHz exceeding USB 3.0 test board measurement requirements.

Application: Functional and interface testing of ASIC, Signal characterization, performance analysis, pre-bringup, pre-compliance test.

ZX230BR



2nd generation of ZX230BR, best in class SuperSpeed USB 3.0 (Backward compatible with HSIC USB 2.0) test board. Using USB 3.0 **Type B Receptacle** (Socket) connector meeting electrical compliance testing—eye diagram, jitter (random) deterministic, total jitter, SCC profiles tests, Slew Voltage levels and more). Designed In 4 layers 100 Ω differential trace impedance measuring insertion loss of 3.8dB at 5GHz exceeding meeting USB 3.0 test board measurement requirements.

Application: Functional and interface testing of ASIC, Signal characterization, performance analysis, pre-bringup, pre-compliance test.

ZX230ABR

2nd generation of ZX230ABR, best in class SuperSpeed USB 3.0 (Backward compatible with HSIC USB 2.0) test board. Using USB 3.0 **Type AB Receptacle** (Socket) connector meeting electrical compliance testing—eye diagram, jitter (random) deterministic, total jitter, SCC profiles tests, Slew Voltage levels and more). Designed In 4 layers 100 Ω differential trace impedance measuring exceptional insertion loss of 2.56dB at 5GHz exceeding USB 3.0 test board measurement requirements, unpresentated .

Application: Functional and interface testing of ASIC, Signal characterization, performance analysis, pre-bringup, pre-compliance test.

ZX230ABP

Introducing ZX230ABP, best in class SuperSpeed USB 3.0 (Backward compatible with HSIC USB 2.0) test board. Using USB 3.0 **Type AB Plug** connector meeting electrical compliance testing—eye diagram, jitter (random) deterministic, total jitter, SCC profiles tests, Slew Voltage levels and more). Designed In 4 layers 100 Ω differential trace impedance measuring exceptional insertion loss of 2.56dB at 5GHz exceeding USB 3.0 test board measurement requirements, unpresentated .

Application: Functional and interface testing of ASIC, Signal characterization, performance analysis, pre-bringup, pre-compliance test.

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